

Status: Path 1 of [Dialog]

Status: Initializing Port COM3 using (Baud 19200 Handshake XON/XOFF DataBits 7 Parity Even StopBits 1)

Status: Initializing modem ...

Status: Initializing modem ...

Status: Initializing modem ...

AT&F2E1Q0V1X4&C1&D2&H2&I2

OK

Status: Dialing primary number (367-0334)...

ATDT367-0334

CONNECT

Status: Modem connection established
14400/ARQ/V32/LAPM

please type your terminal identifier

-4411:01-001-

please log in: DIALOG

DIALOG: call connected

Status: Connected

DIALOG INFORMATION SERVICES

PLEASE LOGON:

***** HHHHHHHH SSSSSSSS?

Status: Signing onto Dialog

ENTER PASSWORD:

***** HHHHHHHH SSSSSSSS? *****

Welcome to DIALOG

Status: Connected

Dialog level 99.04.12D

Last logoff: 21apr99 12:00:14

Logon file405 22apr99 12:16:04

ANNOUNCEMENT **** ANNOUNCEMENT **** ANNOUNCEMENT

NEW

***Miller Freeman Industry and Product News (File 112)

***Irish Times (File 477)

***Business Wire (Files 610 for current news & 810 for archive news)

***Financial Times Abstracts (File 473)

RELOADED

***Kompass Western Europe (File 590)

***HealthSTAR (File 151)

***Aidsline (File 157)

***Medline (Files 154,155)

***EMBASE (Files 72,73)

DIALINDEX

***DIALINDEX categories have been revised. For listing of new/revised categories see <http://library.dialog.com/bluesheets/html/blo.html>.

For more details, see HELP NEWS411.

>>> Enter BEGIN HOMEBASE for Dialog Announcements <<<

>>> of new databases, price changes, etc. <<<

Please enter SUBACCOUNT name/number:

?

Please enter SUBACCOUNT name/number:

?b 351
Is B 351 the SUBACCOUNT you want to use? (Y/N)
?n
Do you want to specify another SUBACCOUNT? (Y/N)
?n
No subaccount set.
***** The DIALORDER suppliers DYNAMIC and FILEDOC are no longer *****
***** in business. Please do not use them. *****

***** File 265: Please use file 266 as file 265 is no longer *****
***** available. *****

***** The MASIS DIALORDER service has been discontinued. For *****
***** details, please contact MARUZEN CO. LTD, at 3-3272-3496. *****

***** Files 100 and 552 have been removed from DIALOG. *****
SYSTEM:HOME
Menu System II: D2 version 1.7.8 term=ASCII
Terminal set to DLINK

*** DIALOG HOMEBASE(SM) Main Menu ***

Information:

1. Announcements (new files, reloads, etc.)
2. Database, Rates, & Command Descriptions
3. Help in Choosing Databases for Your Topic
4. Customer Services (telephone assistance, training, seminars, etc.)
5. Product Descriptions

Connections:

6. DIALOG(R) Document Delivery
7. Data Star(R)

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/H = Help /L = Logoff /NOMENU = Command Mode

Enter an option number to view information or to connect to an online service. Enter a BEGIN command plus a file number to search a database (e.g., B1 for ERIC).

?b 351

22apr99 12:18:53 User144617 Session D436.1
\$0.00 0.103 DialUnits FileHomeBase
\$0.00 Estimated cost FileHomeBase
\$0.60 TYMNET
\$0.60 Estimated cost this search
\$0.60 Estimated total session cost 0.103 DialUnits

File 351:DERWENT WPI 1963-1999/UD=9915;UP=9915;UM=9915

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***File 351: EPI Manual Codes are now available to all users. See**
HELP NEWS 351 for details.

Set	Items	Description
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?s pn=jp 01045131

S1	1	PN=JP 01045131
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?t s1/9

1/9/1

DIALOG(R)File 351:DERWENT WPI

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007831912

WPI Acc No: 89-097024/198913

XRAM Acc No: C89-042948

XRPX Acc No: N89-073802

Washing and oxidising semiconductive wafer - by contacting wafer with supercritical carbon dioxide and then with carbon dioxide, etc.

Patent Assignee: HITACHI LTD (HITA)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Main IPC	Week
JP 1045131	A	19890217	JP 87201720	A	19870814		198913 B

Priority Applications (No Type Date): JP 87201720 A 19870814

Patent Details:

Patent	Kind	Lan	Pg	Filing Notes	Application	Patent
JP 1045131	A		4			

Abstract (Basic): JP 1045131 A

Semiconductive wafer is brought into contact with supercritical carbon dioxide or liquefied carbon dioxide to be washed, and then semiconductive wafer is brought into contact with carbon dioxide including at least one kind of substance having oxygen, or supercritical carbon dioxide gas similar to carbon dioxide gas, to oxidise Si surface of semiconductive wafer.

Washing and oxidising are performed in one tank. Substance having O is O₂, O₃, H₂O or H₂O₃. Supercritical carbon dioxide gas or liquefied carbon dioxide gas used in washing includes at least one kind of substance having O.

USE/ADVANTAGE - Number of times of contact with air in clean room, of semiconductive wafer can be reduced, so that contamination of wafer by air can be decreased, and yield rate in mfr. of semiconductor, can be improved. Washing and oxidising can be performed in one process, so that mfr. is simplified.

1/1

Title Terms: WASHING; OXIDATION; SEMICONDUCTOR; WAFER; CONTACT; WAFER; SUPERCRITICAL; CARBON; DI; OXIDE; CARBON; DI; OXIDE

Derwent Class: E36; L03; U11

International Patent Class (Additional): B01D-011/04; H01L-021/31

File Segment: CPI; EPI

Manual Codes (CPI/A-N): E31-D02; E31-D03; E31-E; E31-N05C; L04-C09

Manual Codes (EPI/S-X): U11-C04A1; U11-C05B1

Chemical Fragment Codes (M3):

01 C101 C106 C108 C408 C530 C550 C730 C800 C801 C802 C803 C804 C805
C807 C810 M411 M782 M903 M904 M910 Q454 R01066-M R01732-M R01779-M
R01887-M

Derwent Registry Numbers: 1066-U; 1732-U; 1779-U; 1887-U

Specific Compound Numbers: R01066-M; R01732-M; R01779-M; R01887-M

?s pn=jp 60192333

S2 1 PN=JP 60192333

?t s2/9

2/9/1

DIALOG(R)File 351:DERWENT WPI

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004453953

WPI Acc No: 85-280831/198545

Stripping-off organic coating-hardening films - such as photoresist-film of semiconductor wafers NoAbstract Dwg 0/2

Patent Assignee: HITACHI LTD (HITA)

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Main IPC	Week
JP 60192333	A	19850930	JP 8447653	A	19840313		198545 B
JP 89044013	B	19890925					198942

Priority Applications (No Type Date): JP 8447653 A 19840313

Patent Details:

Patent	Kind	Lan	Pg	Filing Notes	Application	Patent
JP 60192333	A		8			

Title Terms: STRIP; ORGANIC; COATING; HARDEN; FILM; PHOTORESIST; FILM;

SEMICONDUCTOR; WAFER; NOABSTRACT
Derwent Class: G06; L03; P83; P84; U11
International Patent Class (Additional): G03C-011/00; G03F-007/00;
H01L-021/30
File Segment: CPI; EPI; EngPI
Manual Codes (CPI/A-N): G06-D06; G06-G; L03-D03B
Manual Codes (EPI/S-X): U11-C07
?

Status: Signing Off...

logoff

22apr99 12:23:11 User144617 Session D436.2
\$3.17 0.195 DialUnits File351
\$7.10 2 Type(s) in Format 9
\$7.10 2 Types
\$10.27 Estimated cost File351
\$1.00 TYMNET
\$11.27 Estimated cost this search
\$11.87 Estimated total session cost 0.298 DialUnits

Status: Signed Off. (8 minutes)